Overview

HP 205 G8 24 All-in-One PC

Front

1. Pull-up webcam and microphone
2. Speakers

Overview

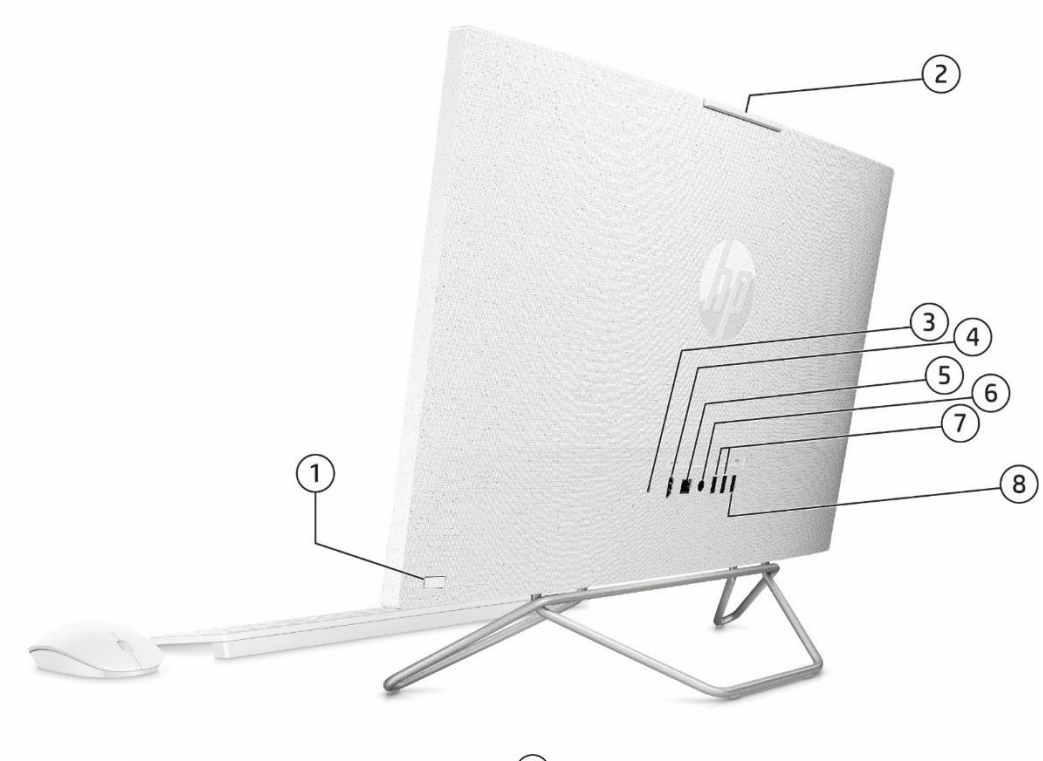
HP 205 G8 24 All-in-One PC

Left side

1. USB SuperSpeed 5 Gbps port with HP Sleep and Charge
2. Microphone/Headphone Combo Jack

Overview

HP 205 G8 24 All-in-One PC



Rear

1. Power button
2. Pull-up webcam
3. Standard cable lock slot
4. HDMI 1.4 out connector
5. RJ-45 (network) jack
6. Power connector
7. Two (2) Type-A Hi-Speed USB 480Mbps signaling rate ports
8. One (1) Type-A SuperSpeed USB 5Gbps signaling rate port

Features

At a Glance

- Choice of different ID: Iron Gray and Starry White[1]
- Choice of Windows 11 Pro, Windows 11 Home, and FreeDOS
- Integrated All-in-One form factor
- 23.8-inch diagonal widescreen Full HD anti-glare display
- Latest AMD® Ryzen™ and Athlon™ Processors with Radeon™ Vega Graphics
- Up to 32GB of DDR4 3200 SODIMM
- Integrated 10/100/1000 Gigabit LAN Ethernet Controller
- Optional Wi-Fi 6 wireless connectivity
- Integrated HD audio card and stereo speakers
- Integrated 5MP pull-up camera to ensure no accidental recording to safeguard user's privacy
- Expandable storage options with up to 1TB SSD and 2TB HDD, including optional 2nd HDD
- Optional HP external USB DVD/RM Drive
- TPM 2.0 support
- Low halogen[2] materials, ENERGY STAR® certified[3] and EPEAT® 2021 registered where applicable.[4]
- Protected by HP Services. Terms and conditions vary by country. Certain restrictions and exclusions apply.

1. Only available in certain regions.
2. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.
3. ENERGY STAR® certified on select configurations
4. Based on EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEMS

Preinstalled	Windows 11 Pro - HP recommends Windows 11 Pro[1] Windows 11 Home[1]
Pre-installed (other)	FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

PROCESSORS*

AMD Ryzen™ 7 5700U[1]
1.8 GHz base clock, up to 4.3 GHz max boost clock
4 MB L2 cache, 8 MB L3 cache, 8 cores
Integrated Radeon™ Graphics
Supports DDR4 memory up to 3200 MHz data rate[2]

AMD Ryzen™ 5 5500U[1]
2.1 GHz base clock, up to 4.0 GHz max boost clock
3 MB L2 cache, 8 MB L3 cache, 6 cores
Integrated Radeon™ Graphics
Supports DDR4 memory up to 3200 MHz data rate[2]

AMD Ryzen™ 3 5300U[1]
2.6 GHz base clock, up to 3.8 GHz max boost clock
2 MB L2 cache, 4 MB L3 cache, 4 cores
Integrated Radeon™ Vega 6 Graphics
Supports DDR4 memory up to 3200 MHz data rate[2]

AMD Ryzen™ 3 3250U[1]
2.6 GHz base clock, up to 3.5 GHz max boost clock
192 KB L1 cache, 1 MB L2 cache, 4 MB L3 cache, 2 cores
Integrated Radeon™ Graphics
Supports DDR4 memory up to 2400 MT/s data rate[2]

AMD Athlon™ Silver 3050U[1]
2.3 GHz base clock, up to 3.2 GHz max boost clock
192 KB L1 cache, 1 MB L2 cache, 4 MB L3 cache, 2 cores
Integrated Radeon™ Graphics
Supports DDR4 memory up to 2400 MT/s data rate[2]

1. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering, branding and/or naming is not a measurement of higher performance.
2. Actual data rate is determined by both the system's configured processor and memory module installed.
NOTE: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

Features

GRAPHICS

Integrated
AMD Radeon™ Vega Graphics

NOTE: AMD integrated Radeon™ Vega Graphics varies by processor

DISPLAY

Non-Touch
23.8" diagonal FHD IPS anti-glare WLED-backlit (1920 x 1080)
23.8" diagonal FHD VA anti-glare WLED-backlit (1920 x 1080)[1]

1. Not available until October 2021.

STORAGE AND DRIVES[1]

M.2 PCIe NMVe Solid State Drives (SSD)
256GB 2280 PCIe NVMe Solid State Drive
512GB 2280 PCIe NVMe Solid State Drive
1TB 2280 PCIe NVMe Solid State Drive
128GB 2280 PCIe NVMe TLC Solid State Drive
256GB 2280 PCIe NVMe TLC Solid State Drive
512GB 2280 PCIe NVMe TLC Solid State Drive

2.5inch SATA Hard Disk Drives (HDD)
1TB 7200RPM 2.5 in HDD
2TB 5400 RPM 2.5 in HDD

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 11) is reserved for system recovery software.

Features

MEMORY

Maximum
DDR4 SODIMM up to 3200MT/s

Memory Slots
2 SODIMM

Available Configurations
4GB (4GB x1)
8GB (4GB x2)
8GB (8GB x1)
16GB (8GB x2)
16GB (16GB x1)
32GB (16GB x2)
32GB (32GB x1)

NOTE: Actual data rate is determined by both the system's configured processor and memory module installed.

NETWORKING/COMMUNICATIONS

Wireless LAN*,**
Realtek® 8852AE Wi-Fi 6[1] (802.11ax) 2x2 Wi-Fi M.2 Card[2]
Realtek® RTL8821CE Wi-Fi 5[1] (802.11ac) 1x1 Wi-Fi M.2 Card[2]

Ethernet (RJ-45) Integrated
Realtek® RTL8111HSH-CG Gigabit Ethernet Controller

*Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 is backwards compatible with prior 802.11 specs.
**Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.
1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels
2. Must be configured at time of purchase.

AUDIO/MULTIMEDIA

High Definition Audio
Integrated Realtek ALC3274 Audio Codec
High performance integrated stereo speakers
3.5mm combo (microphone/headphone) jack

Webcams & Mic
Integrated 5MP webcam, Up to 30 frames/sec, dual array microphone included

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboards
HP Universal USB Wired Keyboard

Mice
HP USB Hardened Optical Mouse
HP USB Universal Mouse

Keyboard and Mouse Combo
HP Universal wireless Keyboard & Mouse combo

NOTE: Availability may vary by country

Features

SOFTWARE AND SECURITY

HP Support
HP PC Hardware Diagnostics
HP Cloud Recovery
HP Support Assistant

Internet Security and Antivirus
McAfee LiveSafe (30-day subscription)[1]

Product Setup
HP JumpStarts

Security Features
Trusted Platform Module (TPM) 2.0 (firmware)[2,3]

Productivity
Xerox® DocuShare® (90 days free trial offer)[4]

1. 30 days trial period. Internet access required to receive updates. First update included. Subscription required for updates thereafter
2. TPM feature will not be supported on machines pre-configured with FreeDOS and Linux
3. In selected countries, machines pre-configured with Windows OS will be shipped with TPM disabled.
4. Simply sign up and start using Xerox® DocuShare® Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 days free trial period. See visit https://xerox.com/docusharego for details.

POWER

Power Supply

HP Smart 65W External AC power adapter
HP Smart 90W External AC power adapter

PORTS/SLOTS

Rear I/O Ports
Two (2) Type-A Hi-Speed USB 480Mbps signaling rate ports
One (1) Type-A SuperSpeed USB 5Gbps signaling rate ports
One (1) RJ-45 (network) jack
One (1) HDMI 1.4 out connector
One (1) DC in power

Side I/O Ports
One (1) Type-A SuperSpeed USB 5Gbps signaling rate ports
One (1) Microphone/Headphone Combo Jack

Internal I/O Ports
One (1) M.2 PCIe x1 2230 (for WLAN)
One (1) M.2 PCIe x4 2280 (for storage)
One (1) SATA storage connector

Bays
One (1) 2.5” internal storage drive

WEIGHTS & DIMENSIONS

Weight

23.8 Non-Touch Product Weight (Unboxed)

Basic Stand	5.37 kg, 11.84 lbs
23.8 Shipping Weight (Boxed)	8.80 kg, 19.40 lbs
23.8 Shipping Weight (Pallet)	225.2 kg, 496.5 lbs

Dimension

23.8 System Dimensions

Without Stand	540.62 x 183.7 x 351.43 mm 21.28 x 7.23 x 13.84 in
Basic Stand	540.62 x 183.7 x 419.01 mm 21.28 x 7.23 x 16.50 in
23.8 Shipping Dimensions (Boxed)	641 x 277 x 525 mm 25.2 x 10.7 x 20.6 in
23.8 Shipping Dimensions (Pallet)	1200 x 1000 x 2235 mm 47.24 x 39.37 x 88 in
23.8 Pallet Quantity (Sea/ Rail)	24
23.8 Pallet Quantity (Air)	12

UNIT ENVIRONMENT AND OPERATING CONDITIONS[9]

• Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
• Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
• Never restrict airflow into the computer by blocking any vents or air intakes.
• Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
• Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
• If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 50° to 95° F (10° to 35° C)* Non-operating: -22° to 140° F(-30° to 60° C)
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50000ft (15240 m)

NOTE: Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

ALL-IN-ONE DISPLAY PANEL SPECIFICATIONS

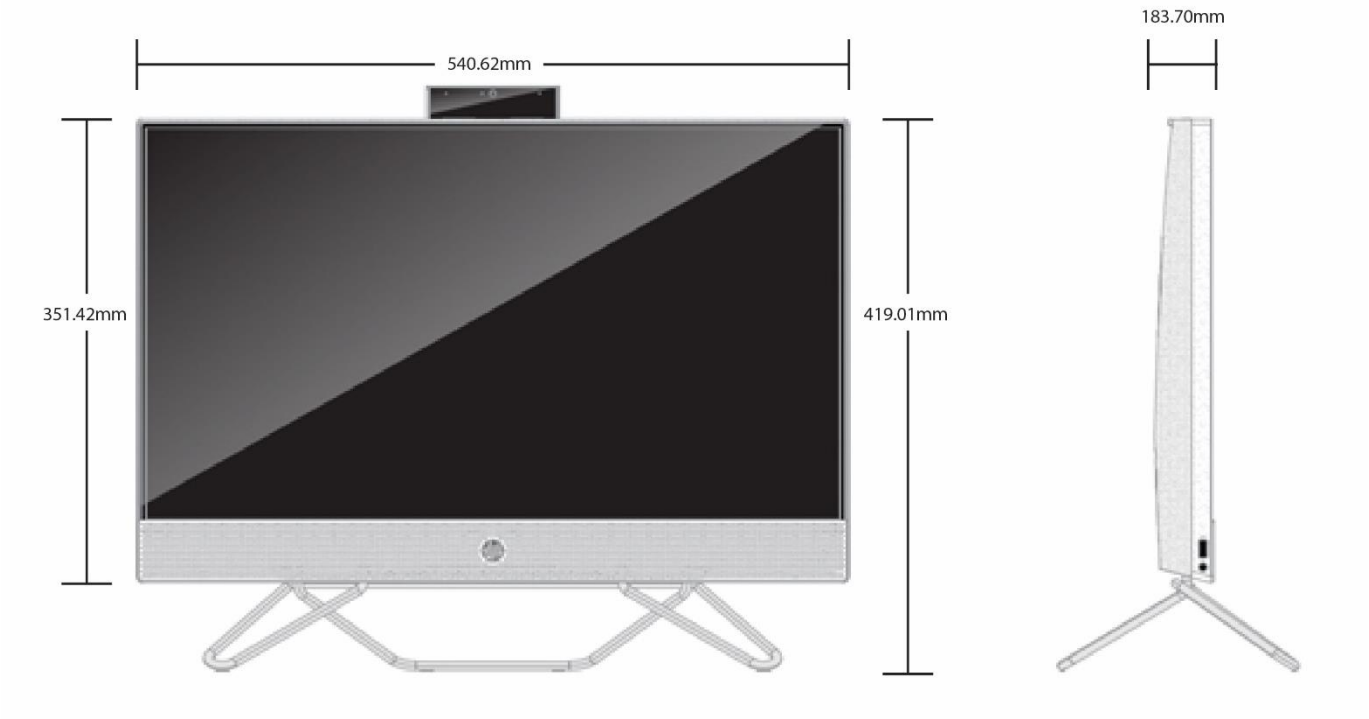
23.8" diagonal FHD IPS anti-glare WLED-backlit (1920 x 1080)
Non-touch

Type	IPS WLED Backlit LCD
Active area (mm)	527.04 x 296.46
Native resolution (HxV)	1920 x 1080
Refresh rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2745 x 0.2745
Contrast ratio (typical)	1000:1
Brightness (typical)	250nits
Viewing angle (typical) (HxV)	178 ° x 178 °
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut (typical)	NTSC 72%
Anti-glare	Yes
Response time (typical)	14ms
Default color temperature	Warm (6500K)

NOTE: All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

ALL-IN-ONE STAND SPECIFICATIONS

Articulating Stand	**Tilt Angle**	-5° to +20°
	Rotation (Swivel)	None
	Pivot	None



STORAGE AND DRIVES

1TB 7200RPM 2.5in SATA HDD

Capacity	1TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	64 MB
Logical Blocks	1,953,525,168
Seek Time	11 ms (Average)
Height	1 in/2.54 cm
Width (nominal)	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131°F (5° to 55°C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2TB 5400RPM 2.5in SATA HDD

Capacity	2TB
Rotational Speed	5,400 rpm
Interface	SATA 6 Gb/s
Buffer Size	64 MB
Logical Blocks	3,907,029,168
Seek Time	11 ms (Average)
Height	1.028 in/26.11 mm
Width (nominal)	4.0 in/101.6 mm
Operating Temperature	41° to 131°F (5° to 55°C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	1TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	1 TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen4
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP EXTERNAL USB DVD/RW

Drive	Manual try load
Interface	USB 2.0
Dimensions (H x W x D)	0.55 X 5.41 X 5.94 in (1.40 X 14.40 X 13.75 cm)
Form factor	External
Access Times CD 1/3 STROKE	140 ms
DVD 1/3 Stroke	160 ms
Supported media (read)	DVD-ROM, DVD-R DVD-R, DVD-R DL, DVD-RW, DVD-RAM, DVD+R, DVD+R DL, AND +RW CD-ROM, CD-ROM XA, CD-DA SUPER AUDIO CD CD-R DISCS CD-RW DISCS CPRM (DVD-R/RW/RAM) SUPPORTED
Supported media (write)	DVD-R DVD-R DL DVD-RW DVD-RAM DVD+R DVD+R DL DVD+RW CD-R/RW
System requirements	Pentium IV 2.4GHz or higher, Compatible (recommended: Pentium IV 3.2GHz or higher)
RAM	256MB or higher (recommended: 128MB)
HDD	20GB or more of available space
Video memory	64MB or higher (recommend: 128MB)
Maximum speed normal	
Write Speeds	DVD-RW 6X MAXIMUM BY ZCLV DVD+RW 8X MAXIMUM BY ZCLV CD-RW 24 X MAXIMUM BY ZCLV
Read Speeds	DVD-R/RW/ROM 8 X MAXIMUM DVD-R DL 8 X MAXIMUM DVD-RAM 6 X MAXIMUM DVD-VIDEO 4 X MAXIMUM M-DISC (DVD+R SL) 8 X MAXIMUM DVD+R/+RW 8 X MAXIMUM DVD+R DL 8 X MAXIMUM CD-R/RW/ROM 24 X MAXIMUM CD-DA 24 X MAXIMUM
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (All conditions, non-condensing)	Temperature (operating, read and write): 41°F to 104°F (5°C to 40°C) Relative Humidity (operating): 10% to 80% Relative Humidity (non-condensing, read): 15% to 85% Relative Humidity (depending on temperature, write): 15% to 85% Temperature (non-operating): -22°F to 104°F (-30°C to 40°C)

	Relative Humidity (non-operating, non-condensing): 10% to 90%
Option kit contents	HP Mobile USB DVD/RW Drive, software, documentation

NOTE: Actual speeds may vary. Intended only for creation and storage of original material and other lawful uses. Double layer discs may not be compatible with many existing single layer DVD drives and players.

HIGH DEFINITION AUDIO

Type	Integrated
HD Audio Codec	Realtek ALC3274 Audio Codec
Audio I/O Ports	Rear 3.5mm combo (microphone/headphone) jack (32 Ohm) supporting CTIA and OMTP style headset Microphone (2K Ohm)
Analog Audio	Yes
Internal Speaker Amplifier	2W per channel stereo amplifier for the internal speakers only
Internal Speaker	Yes - Stereo Speaker
DAC Sampling Rates	44.1 kHz/48 kHz/96 kHz/192 kHz
ADC Sampling Rates	44.1 kHz/48 kHz/96 kHz/192 kHz

INPUT/OUTPUT DEVICES

HP Wireless Keyboard

Physical Characteristics	Keys	104, 105 lay out (depending upon country)
	Dimensions (L x W x H)	18.15 x 6.02 x 1.08 in (461 x 153 x 27.4 mm)
	Weight	1.32 lb (600g) min
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Mid-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
	Acoustics	43-dBA maximum sound pressure level
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence

Technical Specifications – Input/Output

HP USB Wireless Mouse		
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)	
Weight	0.19lb (90g)	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	50 g, 6 surfaces
	Non-operating shock	80 g, 6 surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max
	Resolution	800, 1200, 1600 DPI
	Tracking speed	31 inch/sec (max)
	Tracking acceleration	8G(max), 1G=9.8m/s3
Mechanical	Connector	USB 2.0
	Cable length	6 ft (1.8 m)

Technical Specifications – Input/Output

HP Universal USB Wired Keyboard

Physical Characteristics	Keys	104, 105 layout (depending upon country)
	Dimensions (L x W x H)	18.15 x 6.02 x 1.08 in (461 x 153 x 27.4 mm)
	Weight	1.32 lb (600g) min
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Mid-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
	Acoustics	43-dBA maximum sound pressure level
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence

Technical Specifications – Input/Output

HP USB Universal Wired Mouse

Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)	
Weight	0.19lb (90g)	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	50 g, 6 surfaces
	Non-operating shock	80 g, 6 surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max
	Resolution	800, 1200, 1600 DPI
	Tracking speed	31 inch/sec (max)
	Tracking acceleration	8G(max), 1G=9.8m/s3
Mechanical	Connector	USB 2.0
	Cable length	6 ft (1.8 m)

Technical Specifications – Input/Output

HP USB Optical Mouse		
Dimensions (H x L x W)	4.53 x 2.50 x 1.40 in (115 x 63.46 x 35.48 mmm)	
Weight	0.18lb (80g)	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max
	Resolution	1,000 DPI
	Sensor	Pixart PAN3606DL
	Tracking speed	30 inch/sec (max)
	Tracking acceleration	9G(max), 1G=9.8m/s2
Mechanical	Connector	USB 2.0
	Cable length	6 ft (1.8 m)

NETWORKING/COMMUNICATIONS

Realtek® RTL8111HSH-CG Gigabit Ethernet Controller	**Ethernet Features**	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCI Express 1.1 x1 to fully support ASPM L0s/L1 and CLKREQ
	NIC Device Driver Name	PCIe GBE Ethernet Family Controller

WLAN*

Realtek® 8852AE Wi-Fi 6[1] (802.11ax) 2x2 with Bluetooth® M.2	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi® certified
Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz

	• 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: max 300Mbps • 802.11ac : max 866.7Mbps • 802.11ax : max 1201Mbps
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security[2]	• IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[3]	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ax HE40(2.4GHz): +10dBm minimum • 802.11ax HE80(5GHz): +10dBm minimum
Power Consumption	• Transmit mode:2.5 W • Receive mode:2 W • Idle mode: (PSP) 180 mW (WLAN Associated) • Idle mode:50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[4]	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum •802.11ax, MCS11(HE40): -57dBm maximum •802.11ax, MCS11(HE80): -54dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard

Technical Specifications - Networking

Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	

1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. Only available in countries where 802.11ax is supported.
2. Check latest software/driver release for updates on supported security features.
3. Maximum output power may vary by country according to local regulations.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1 Compliant/5.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies

	LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.1 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range

Technical Specifications - Networking

Realtek RTL8821CE Wi-Fi 5[1] (802.11ac) 1x1 with Bluetooth® M.2	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
Interoperability	Wi-Fi® certified
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security[2]	• IEEE 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[3]	• 802.11b: +14dBm minimum • 802.11g: +12dBm minimum • 802.11a: +12dBm minimum • 802.11n HT20(2.4GHz): +12dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +10dBm minimum • 802.11n HT40(5GHz): +10dBm minimum • 802.11ac VHT80(5GHz): +10dBm minimum
Power Consumption	• Transmit mode2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[4]	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum

	802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum	
Antenna type	High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
2. Check latest software/driver release for updates on supported security features.
3. Maximum output power may vary by country according to local regulations.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth® 4.0/4.1/4.2 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode

	LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

POWER

Efficiency	65W EPS, 88% average efficiency at 115V & 89% at 230Vac
Operating Voltage Range	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac
Rated Line Frequency	50Hz~60Hz
Operating Line Frequency	47Hz~63Hz
Rated Input Current	≦1.6A
Rated Input Current with Energy Efficient* Power Supply	≦1.6A
DC Output	+19.5V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-Patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-Patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Dimensions	102 x 55 x 30 mm

Efficiency	90W EPS, 88% average efficiency at 115V & 89% at 230Vac
Operating Voltage Range	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac
Rated Line Frequency	50Hz~60Hz
Operating Line Frequency	47Hz~63Hz
Rated Input Current	≦1.6A
Rated Input Current with Energy Efficient* Power Supply	≦1.6A
DC Output	+19.5V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-Patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-Patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Dimensions	102 x 55 x 30 mm

ADDITIONAL FEATURES

	Description
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country*.

NOTE*: Based on EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".

Energy Consumption (in accordance with US ENERGY STAR® test method)

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			

NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are certified with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options.

Heat Dissipation*

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)
Typically Configured – Idle		
Fixed Disk – Random writes		

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:
Mercury greater the1ppm by weight
Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)
Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 38.3% post-consumer recycled plastic (by wt.)
- This product is 95.8% recycle-able when properly disposed of at end of life.

Packaging Materials

External: PAPER/Corrugated

Internal: PLASTIC/EPE (Expanded Polyethylene)
PLASTIC/Polyethylene low density

The plastic packaging material contains at least 90% recycled content.

The corrugated paper packaging materials contains at least 80% recycled content.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.

- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report
http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
Eco-label certifications
http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
ISO 14001 certifications:
http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
and
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SUMMARY OF CHANGES

Date of change:	Version History:		Description of change:
September 23, 2021	V1 to V2	Update	EPEAT disclaimer
October 14, 2021	V2 to V3	Update	OPERATING SYSTEMS section
December 9, 2021	V3 to V4	Update	WI-fi6 disclaimers updated
May 17, 2022	V4 to V5	Update	Call out images changed to white ones
May 25, 2022	V5 to V6	Update	Feature and disclaimer added to At a glance section
June 2, 2022	V6 to V7	Update	Black all out images added

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